



AVL e-Drive

Air cooled Power electronic design

PDiM 2018 Sweden - Göteborg

F. Haag, S. Pruefling

AVL e-Drive

Development services and competences for advanced e-Drives



Concepts

Components

Hardware

Software

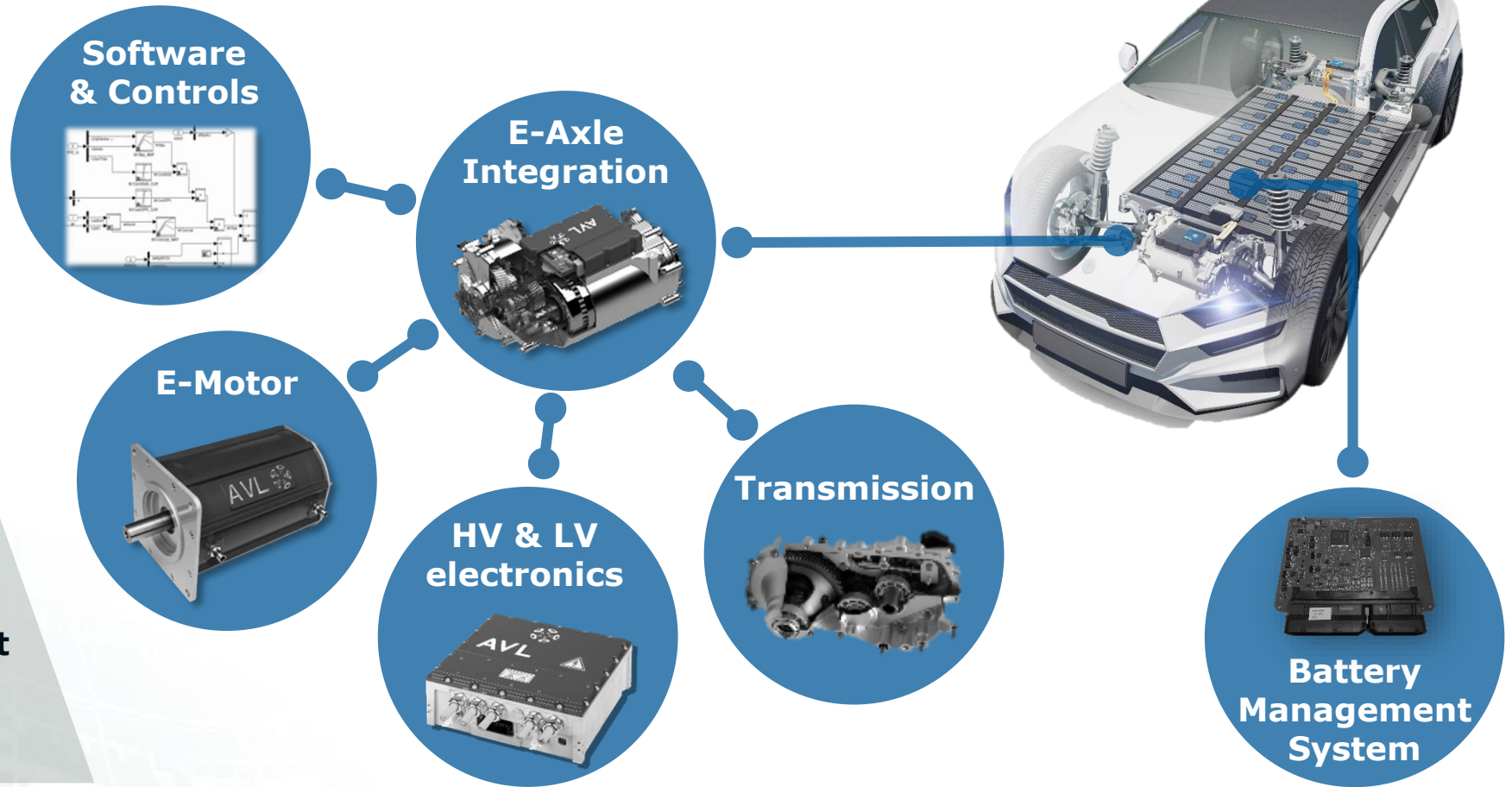
Integration

Benchmarking

Technology consulting

Industrialization support

SOP development



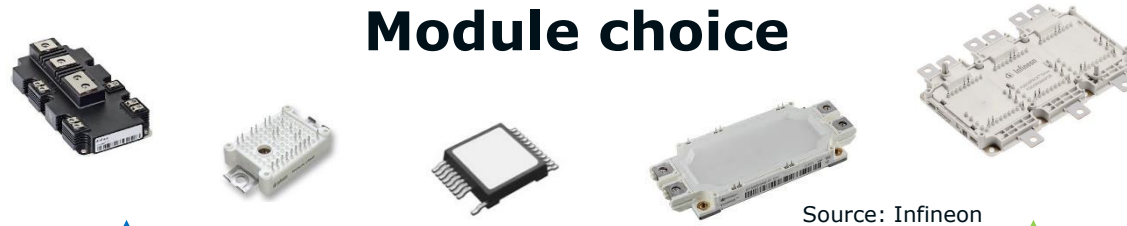
Full solution offering from concept, components to fully integrated E-Drive systems

AVL e-Drive

How to select a cooling system for power electronics?

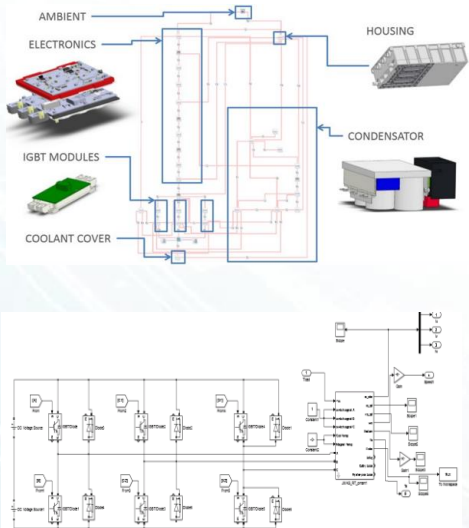


Module choice

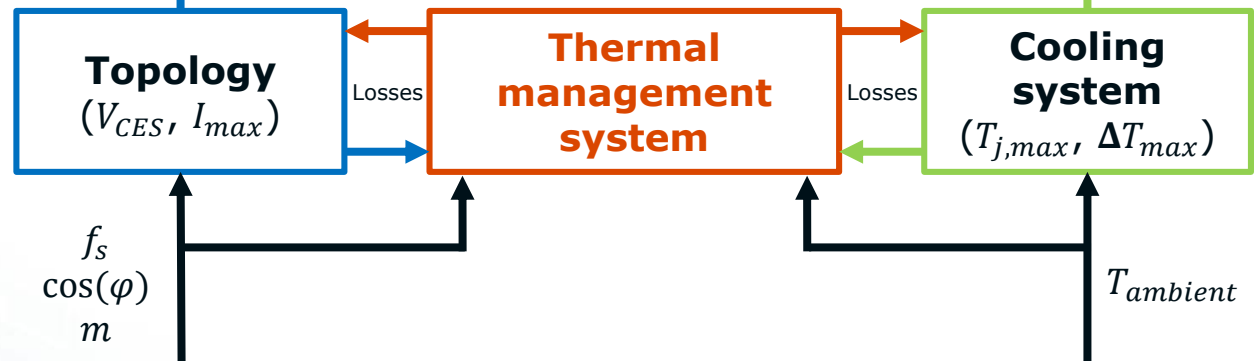
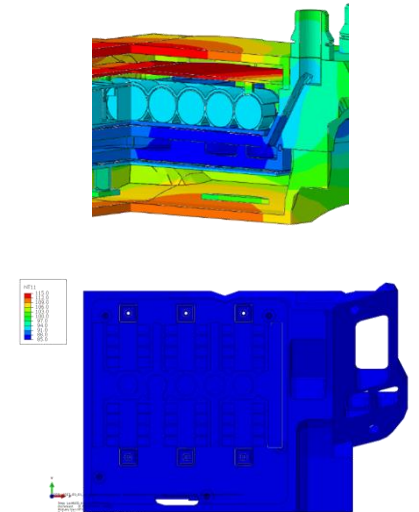


Source: Infineon

Electrical design

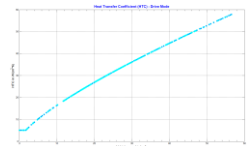


Thermal design



Requirements & Load profile

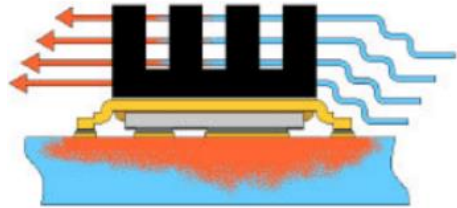
- Ambient air
- HTC
- Vehicle parameters
- ...



Cooling of power electronics is a system topic

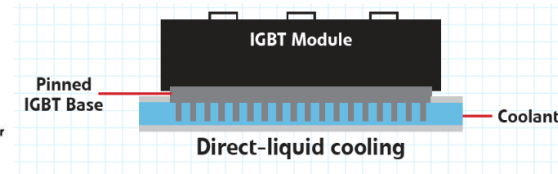
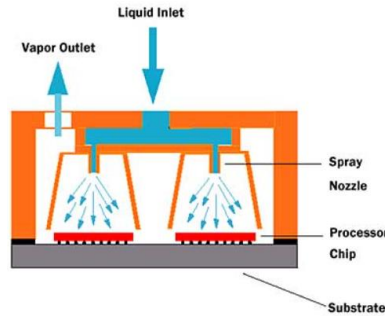
AVL e-Drive

Cooling solutions for power electronics in today's use



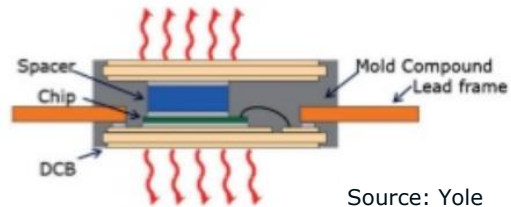
Source: electronics-cooling

Natural and forced convection air cooled head sinks



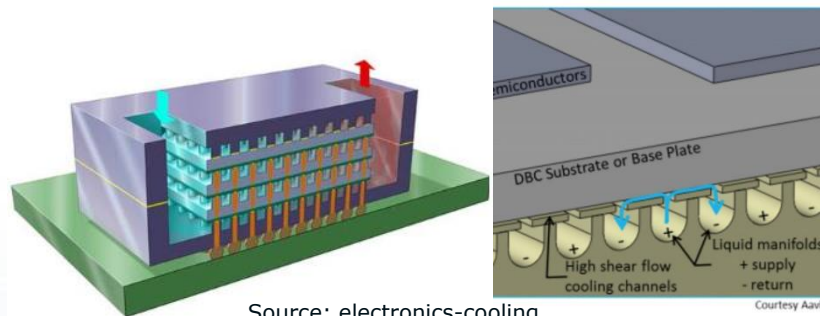
Source: zuerich-ibm

Jet impingement and direct contact liquid cooling of module base plates or DBC substrates



Source: Yole

Single and double sided cooling with liquid cold plates



Source: electronics-cooling

Micro-channel liquid coolers built into power module base plates or integrated with the DBC substrate



Source: luscombe

Two-phase liquid cold plates with boiling of dielectric refrigerant coolant

AVL e-Drive

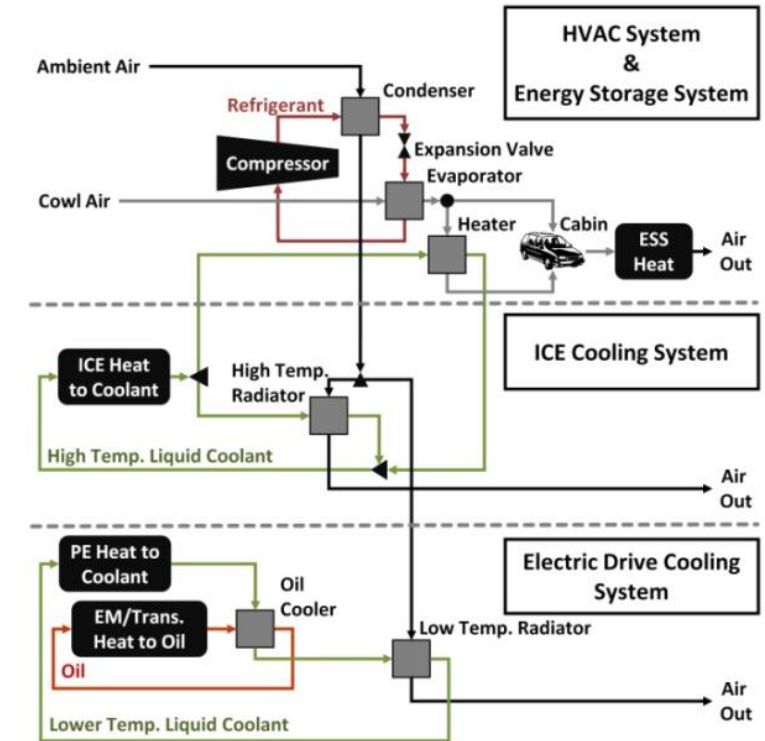
Why air cooling?



Natural or forced air cooling has several benefits such as...

- ✓ Lower system complexity by removing of water pumps, pipes, interfaces, etc.
- ✓ Cost benefit and reduction on system level
- ✓ No leakage compared to liquid cooling possible
- ✓ Good integration possibilities especially in (P)HEVs because of no interfacing of existing cooling system necessary

Today's vehicles are indirect air cooled (heat exchanger)



Example of vehicle cooling system

High potential of air cooling for lower system complexity and cost reduction

AVL e-Drive

What package of semiconductors for air cooling?

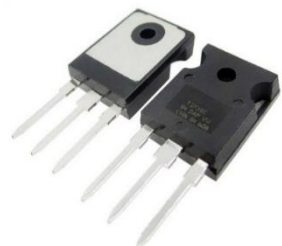


IPU Cooling Interface @ WATER- and AIR-COOLING

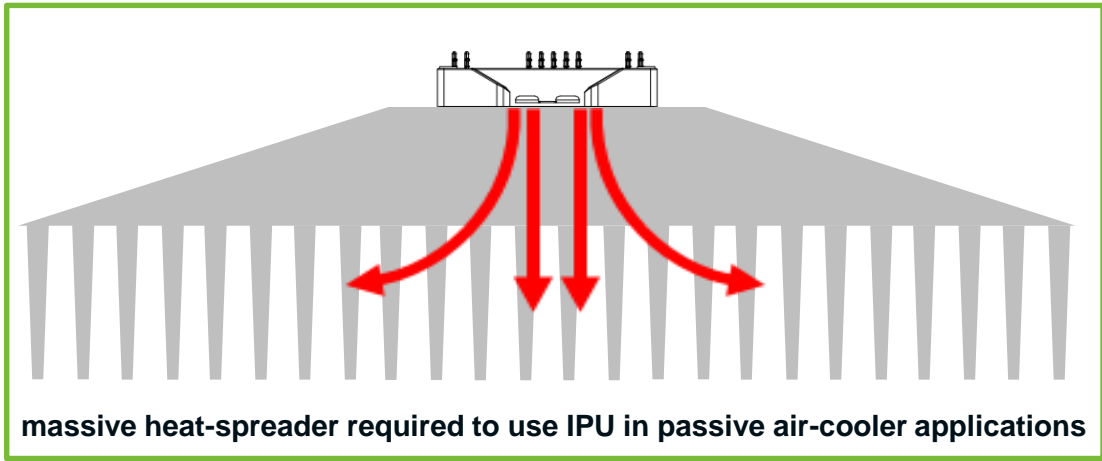


IPU optimized for local interface to heatsink (water-cooler)

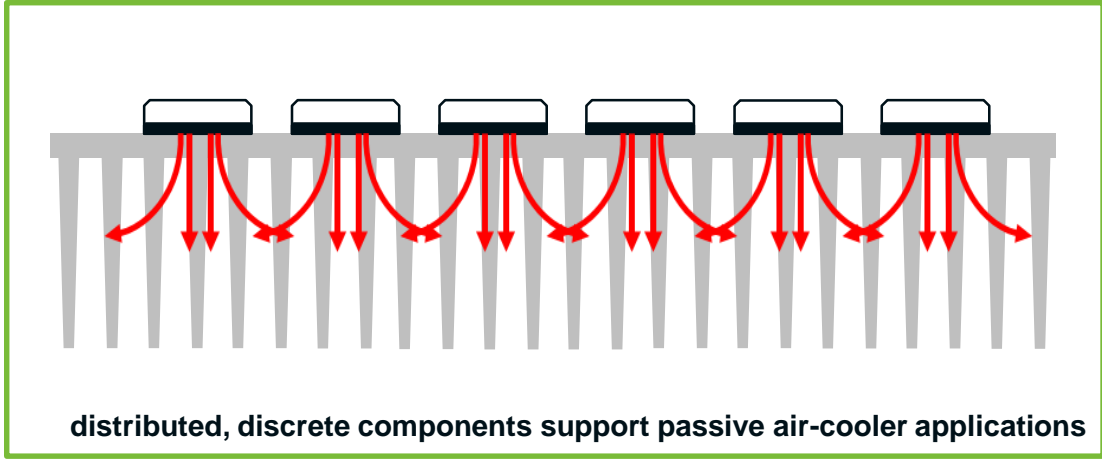
Discrete Semiconductors @ AIR-COOLING application



discrete components to distributed thermal losses homogenously



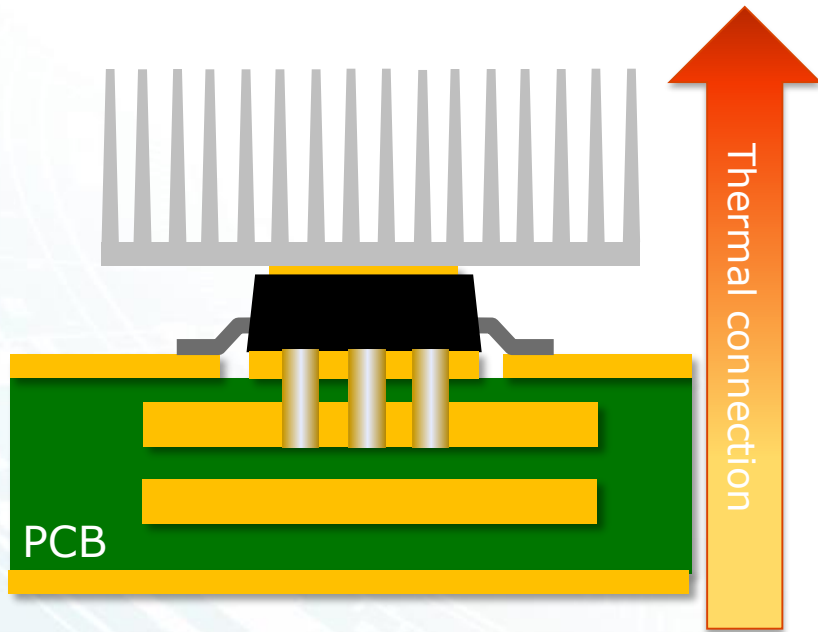
massive heat-spreader required to use IPU in passive air-cooler applications



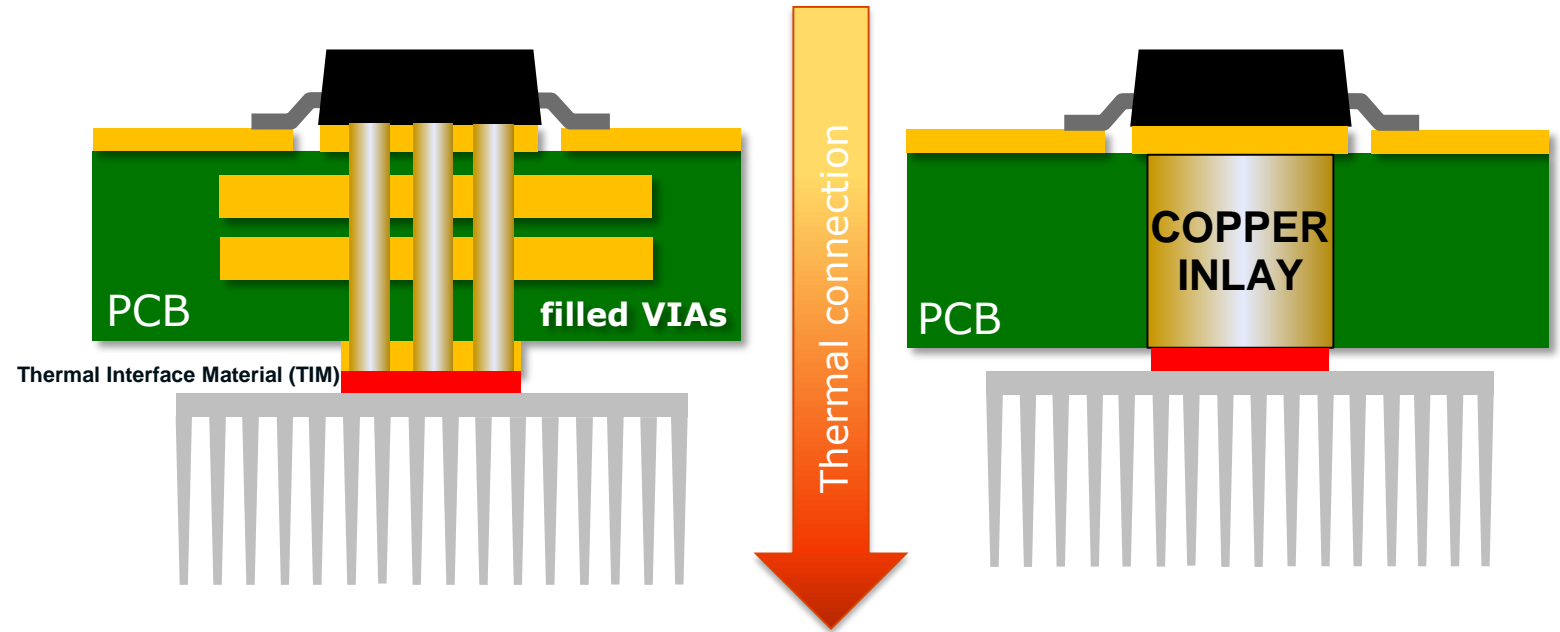
distributed, discrete components support passive air-cooler applications

Especially for air cooling discrete semiconductors supports better equal heat distribution

Typical thermal connection



Alternative thermal connection

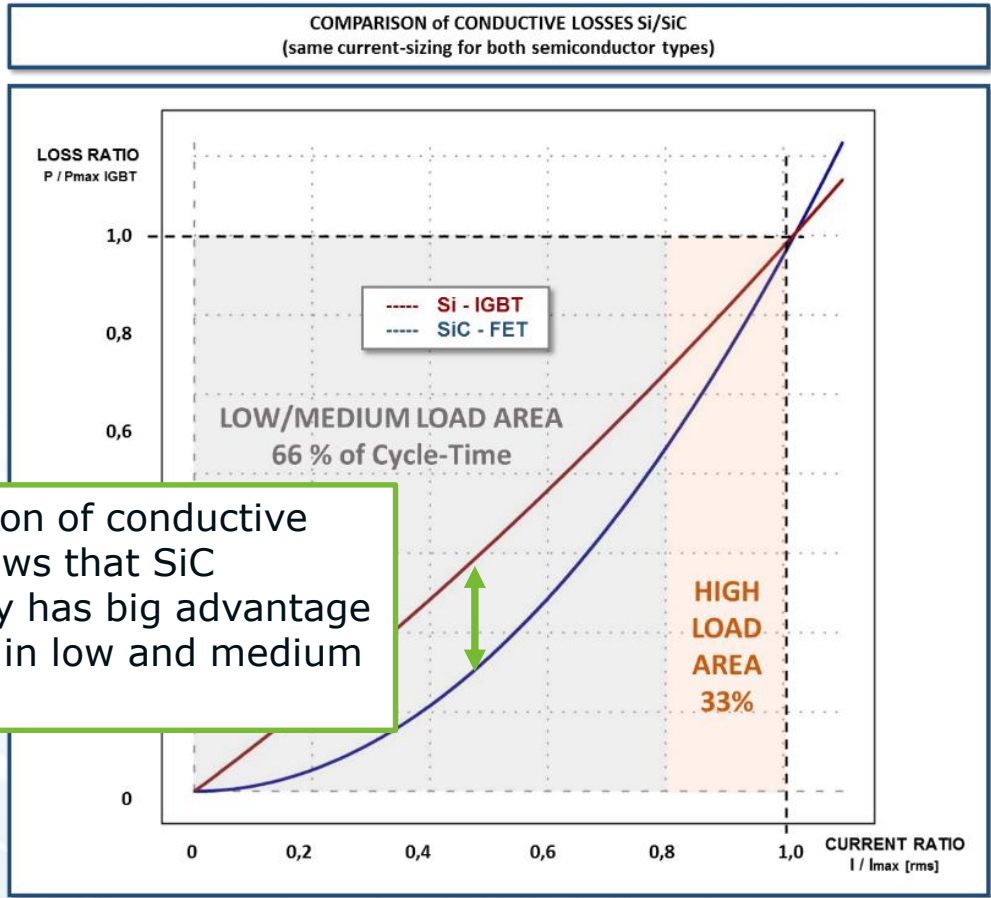


Integration of busbars possible → cooling of busbars

Thermal design also effects the PCB design and layout

AVL e-Drive

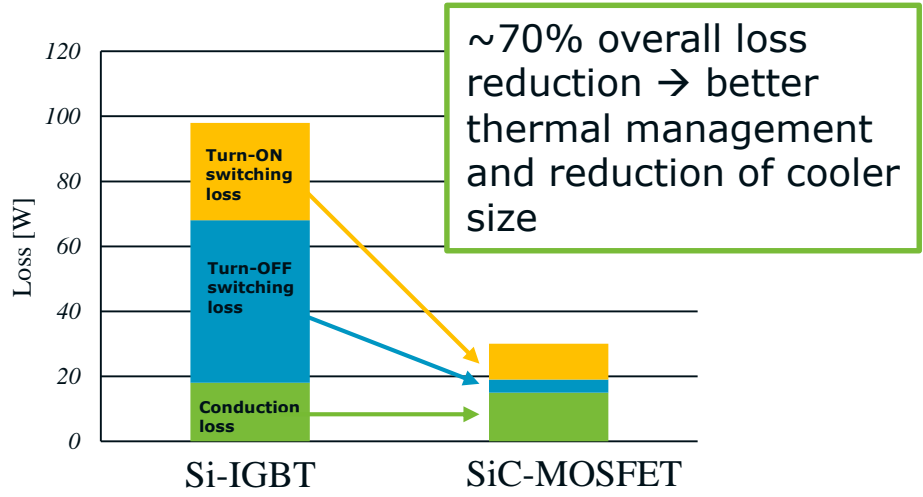
What type of semiconductor technology? Advantages of SiC for air cooling



Visualization of conductive losses shows that SiC technology has big advantage especially in low and medium load area

At a switching frequency similar to current IGBT inverter applications a SiC Converter shows

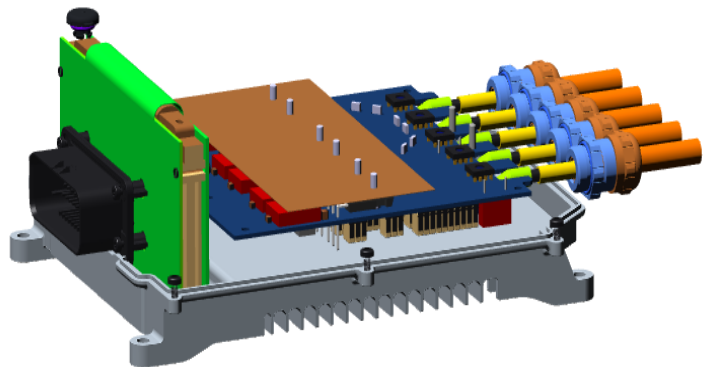
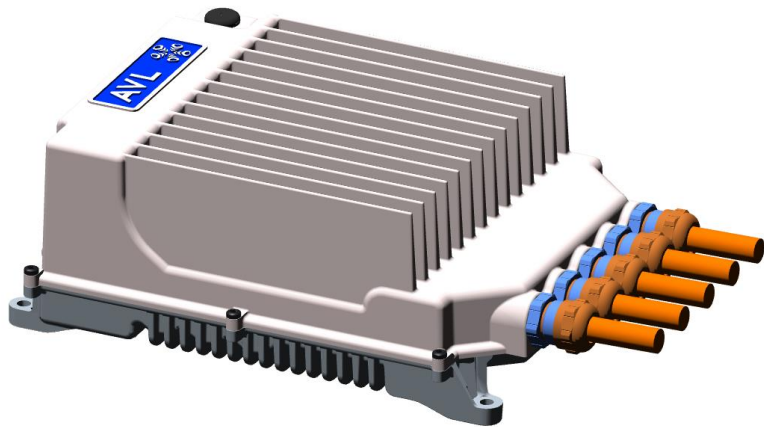
- Lower losses -> less internal temperature increase **AND**
- Better thermal conductivity
- Accepts higher junction temperature up to 200°C



SiC has better thermal properties and therefore big advantages for air cooled applications

AVL e-Drive

Air cooling example: 800V SiC Inverter for auxiliary applications



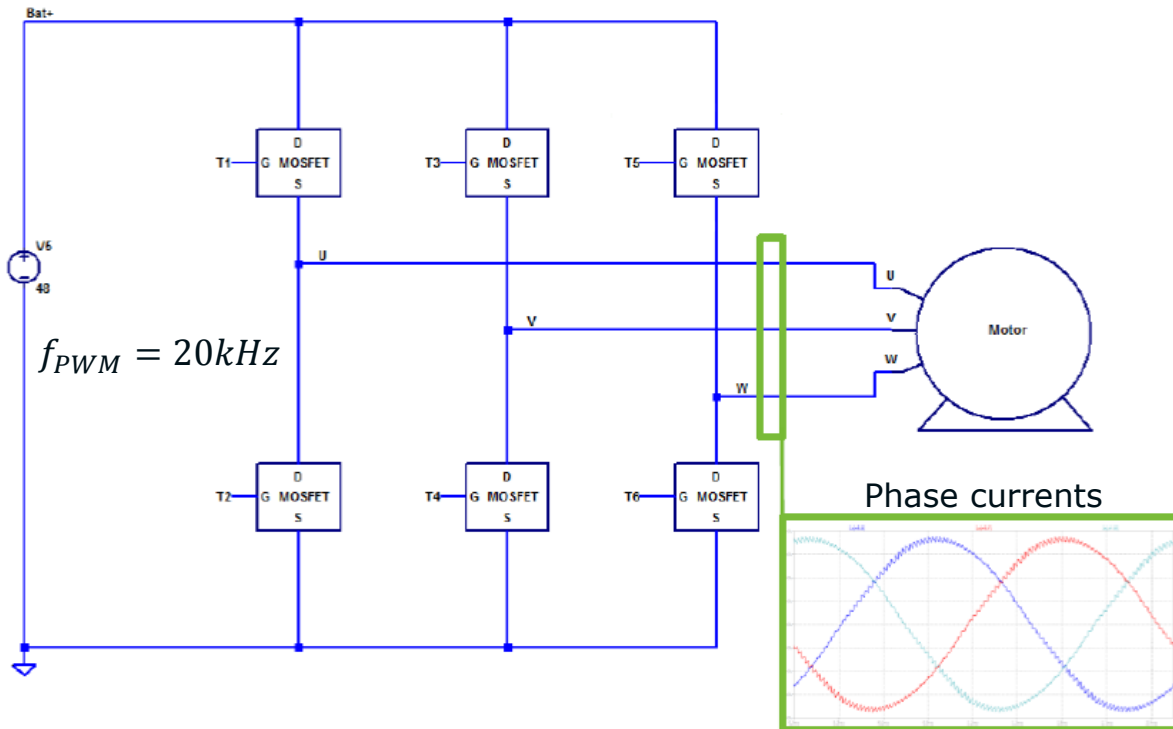
- **Development of 800V SiC inverter for auxiliary components like e-charger, e-compressor**
- **Design to Cost**
- **Separated Control and Powerboard for better EMC-characteristics**
- **Key specifications**
 - No. of phases 3
 - V_{DC} 485-920V
 - V_{nom} 800V
 - $P_{out, max}$ 22kW
 - I_{nom} 15A_{rms}

AVL e-Drive

Semiconductor loss calculation



- Loss simulation based on critical load points
- Mosfet model from supplier for simulation



Inverter conductive losses are defined as:

$$P_{loss,conductive} = I^2 R_{DSon} + 2 \left(\frac{I}{2} \right)^2 R_{DSon}$$

Inverter switching losses are defined as:

$$P_{loss,switching} = 6 f_{PWM} (E_{on} + E_{off})$$

Total losses of Inverter:

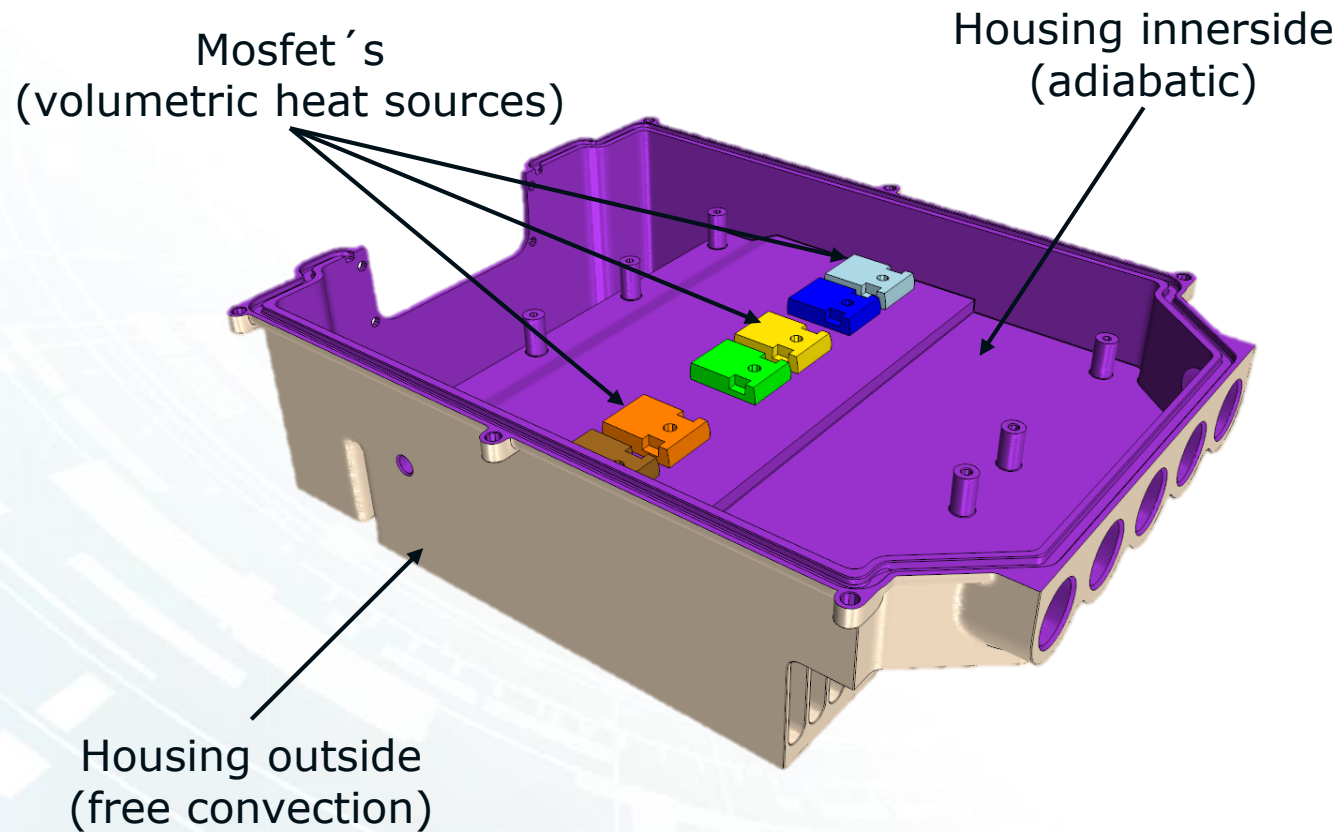
$$P_{loss,total} = I^2 R_{DSon} + 2 \left(\frac{I}{2} \right)^2 R_{DSon} + 6 f_{PWM} (E_{on} + E_{off})$$

Mean value of losses per Mosfet:

$$P_{loss,Mosfet} = \frac{1}{2} I^2 R_{DSon} + f_{PWM} (E_{on} + E_{off})$$

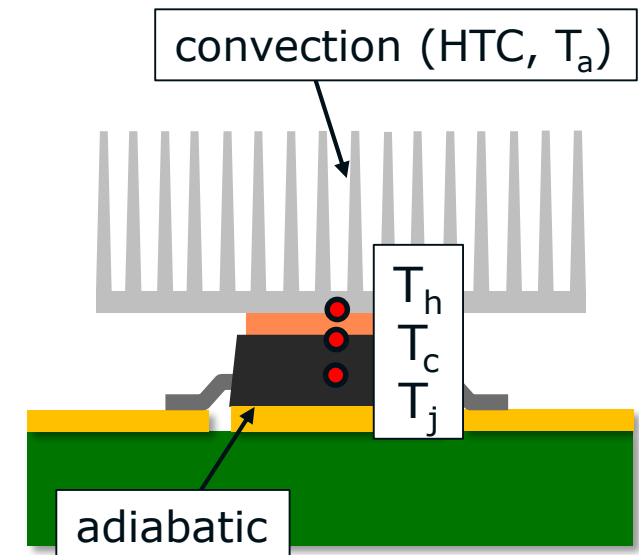
AVL e-Drive

Thermal model of inverter

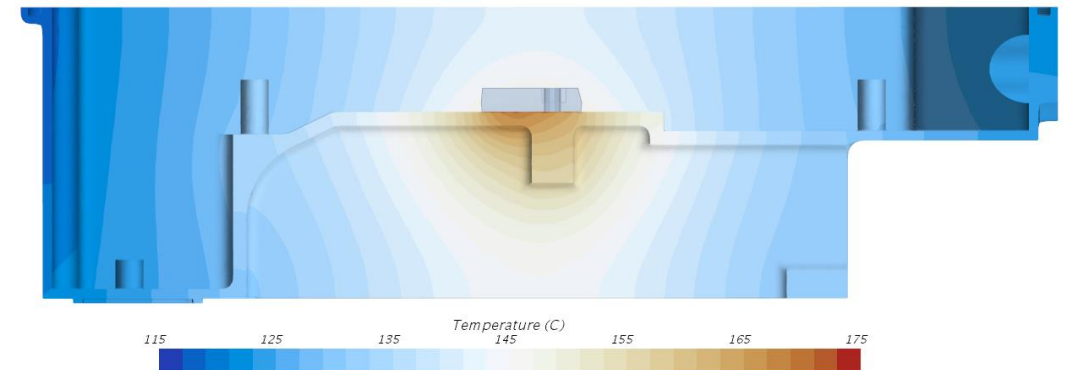
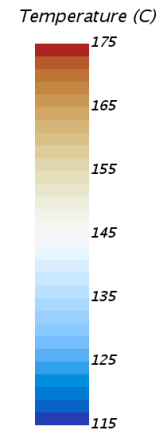
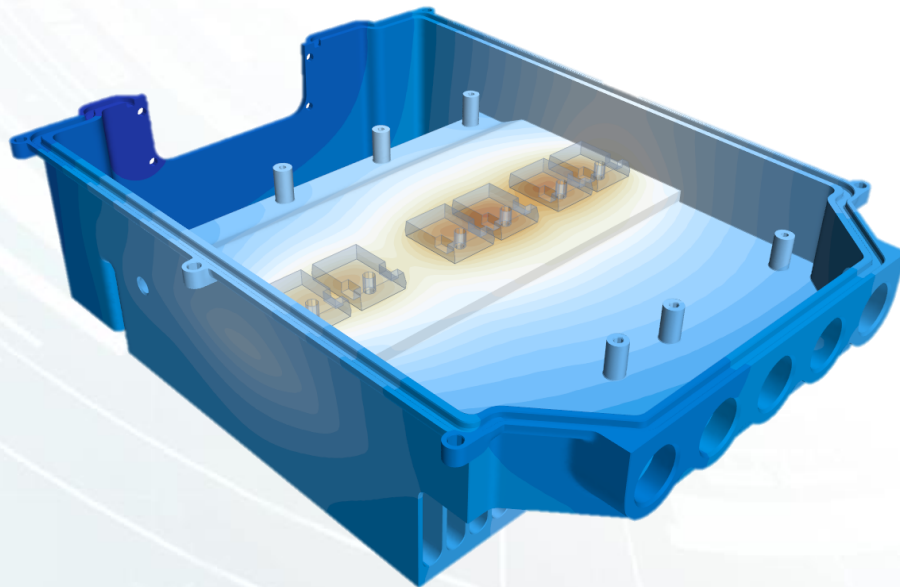


Gappad between Mosfet and housing is modelled as heat resistance

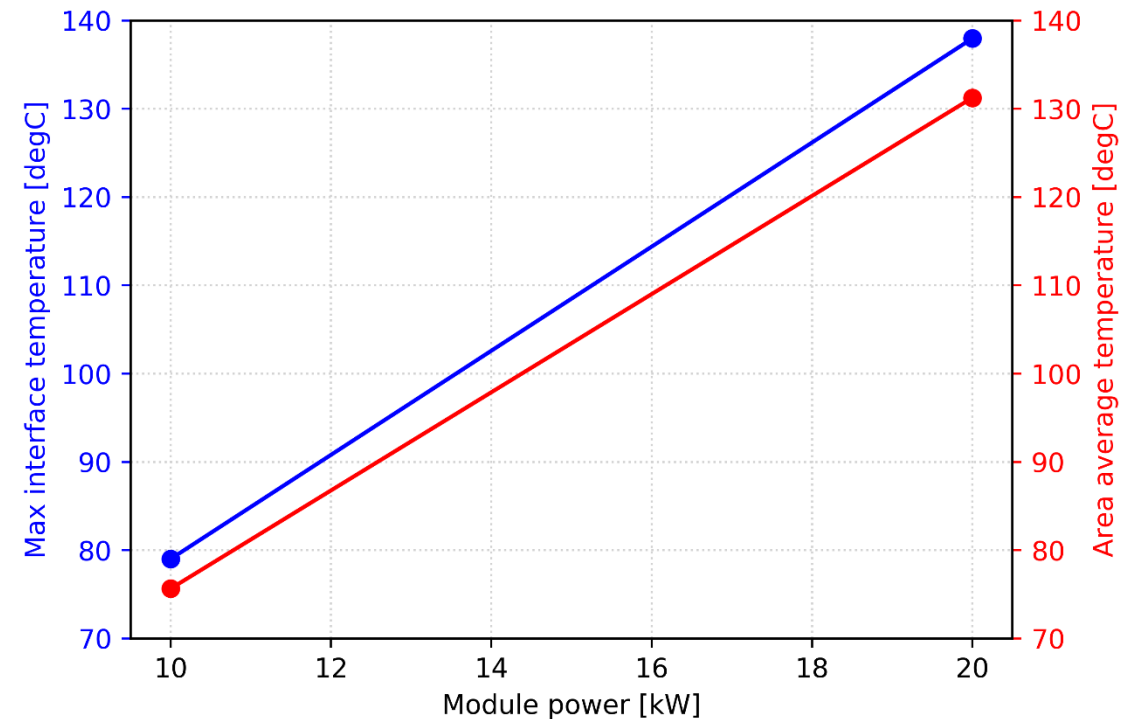
- Heat transfer coefficient of the housing: $HTC = 10 \frac{W}{m^2K}$, (free convection)
- Ambient temperature: $T_{ambient} = 20^\circ C$
- Gappad (Kerafol U90 s=0,2mm): $d = 0.2mm, k = 6 \frac{W}{mK}$
- Housing (AlMg4.5Mn0.7 EN AW - 5083): $k = 125 \frac{W}{mK}$
- R_{mosfet} : $0.55^\circ C/W$ (junction-case resistance)



- Max. power at **200°C** junction temperature is **26.4kW** based on the numerical simulation
- The Mosfet's have a power losses of **270W**
- Max. surface temperature of Gappad is **176 °C**.



- Max. temperature at the Gappad is **79 °C** and **138 °C** for **10** and **20 kW** module power
- The corresponding junction temperature is **88.2 °C** at **10 kW** and **156 °C** at **20 kW**
- The average surface temperature is for **10** and **20 kW** module power a surface temperature of **76 °C** and **131 °C**.



For the planned operating performances, the power module is at a safe distance from its max. allowed limit temperature

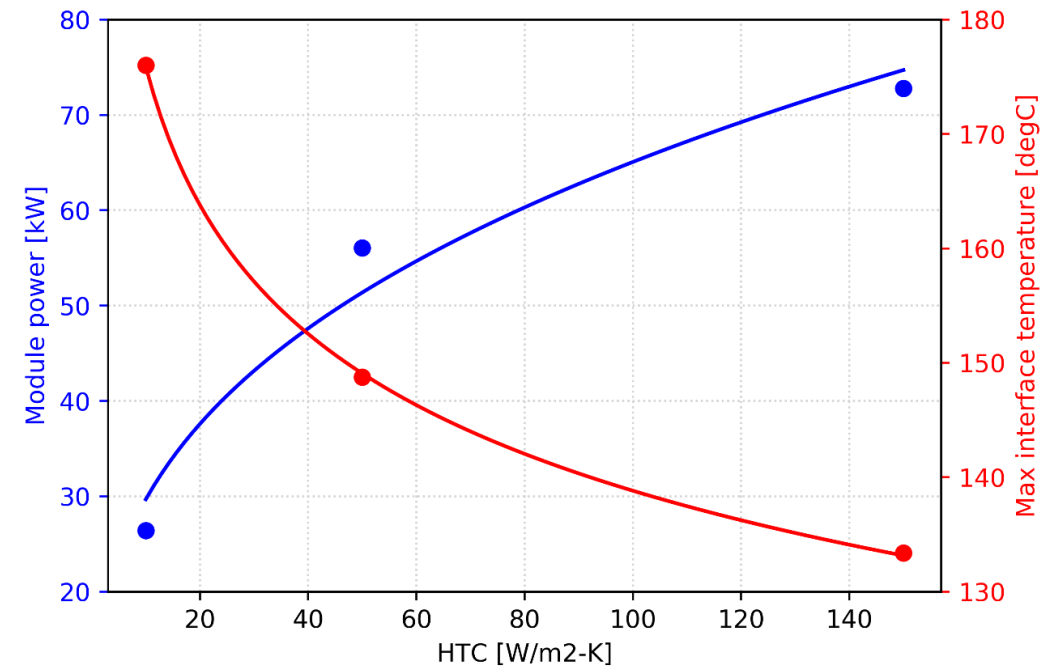


- Investigation of different HTC:
 - 10 W/m²-K (free convection) **26.4 kW**
 - 50 W/m²-K (low air flow) **56.1 kW**
 - 150 W/m²-K (High air flow) **72.8 kW**
- Erhaltene Equations for module power and max. temperature of gappad:

$$P_{Module} = 13.541 \cdot HTC^{0.341}$$

$$T_{Max_if} = 222.841 \cdot HTC^{-0.103}$$

The air flow has the biggest impact for the max. possible power of the inverter



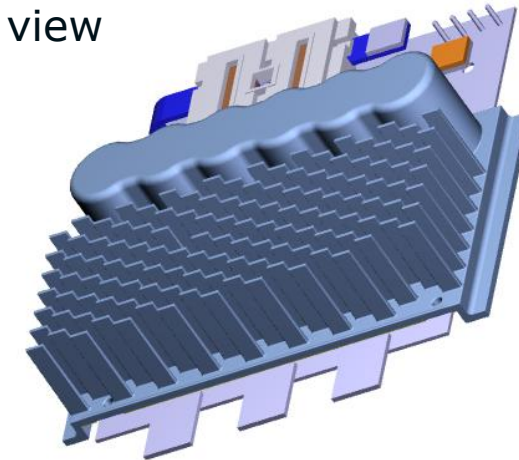
AVL e-Drive

Air cooled Example: 48V Crosscharger

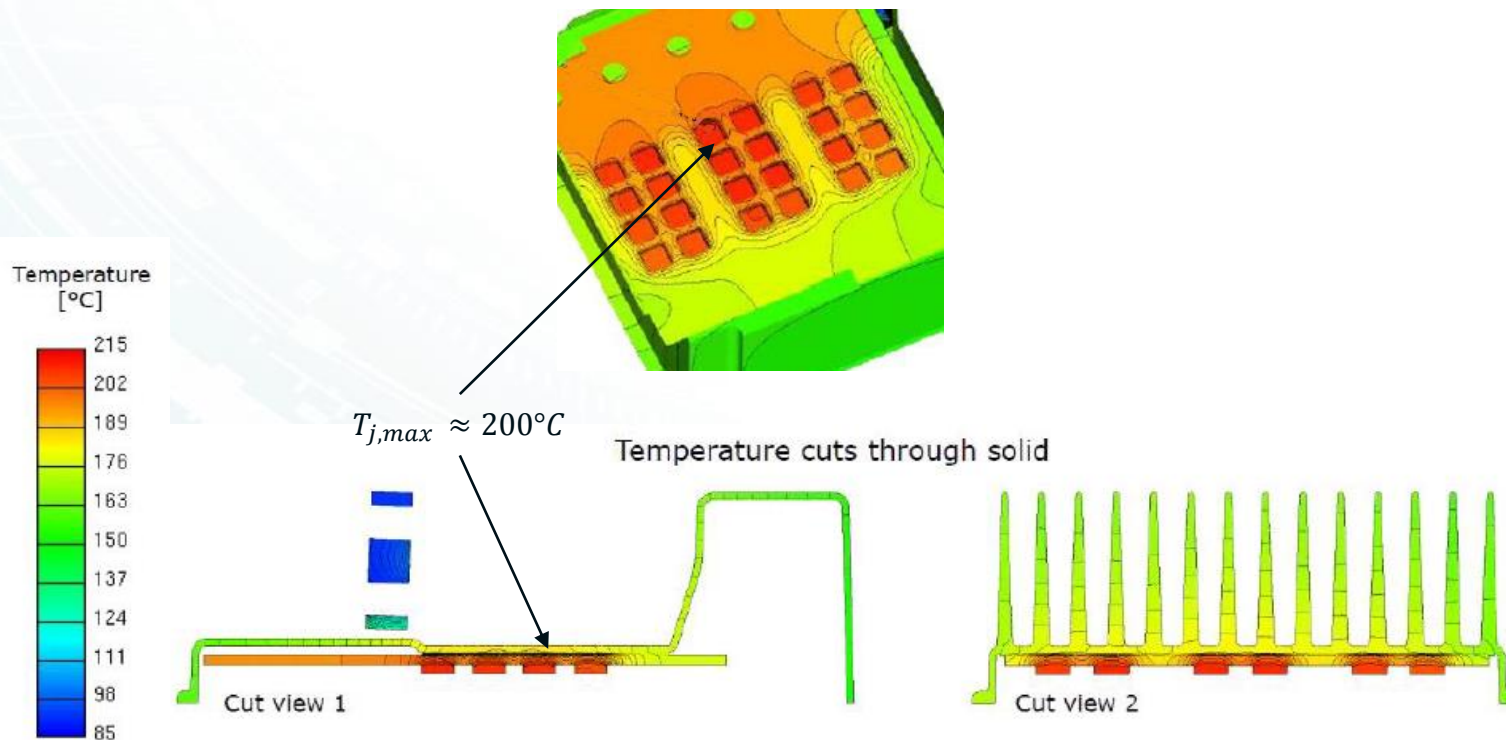
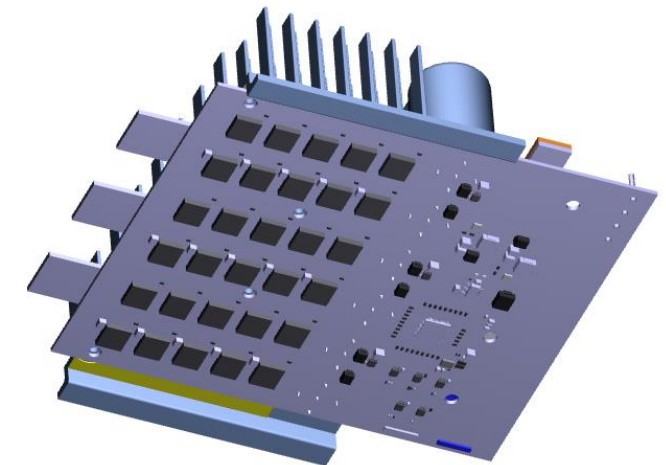


- For the ideal vorticity (turbulent air flow) of the air the housing is designed as "pin fin"
- 4 parallel Mosfets per single switch

Top view



Bottom view



Thank You



www.avl.com

